



# YETDA INDUSTRY LTD.

## Technical Data Sheet

**MODEL NO: 170SR2-G****2.0\*1.25mm Chip LED****Features :**

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

**Applications :**

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

| Dice material | Emitted color | Lens Color     |
|---------------|---------------|----------------|
| AlGaAs/GaAs   | Red           | White diffused |

**Electrical/Optical Characteristics(Ta=25°C )**

| Parameter                           | Test Condition       | Symbol         | Value |     |     | Unit |
|-------------------------------------|----------------------|----------------|-------|-----|-----|------|
|                                     |                      |                | Min   | Typ | Max |      |
| Wavelength at peak emission         | I <sub>F</sub> =20mA | λ peak         |       | 660 |     | nm   |
| Dominant wavelength                 | I <sub>F</sub> =20mA | λd             | 630   | 640 | 650 | nm   |
| Spectral half bandwidth             | I <sub>F</sub> =20mA | Δλ             |       | 20  |     | nm   |
| Forward voltage                     | I <sub>F</sub> =20mA | V <sub>F</sub> | 1.7   | 1.8 | 2.5 | V    |
| Luminous intensity                  | I <sub>F</sub> =20mA | I <sub>V</sub> | 5.0   | 12  | 25  | mcd  |
| Viewing angle at 50% I <sub>V</sub> | I <sub>F</sub> =10mA | 2θ 1/2         |       | 120 |     | Deg  |
| Reverse current                     | V <sub>R</sub> =5V   | I <sub>R</sub> |       |     | 10  | μA   |

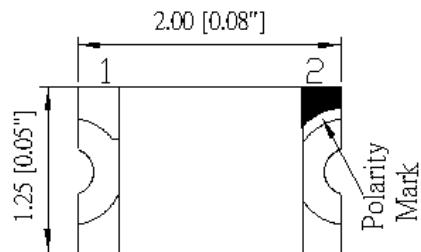
**Absolute Maximum Ratings(Ta=25°C )**

| Parameter                              | Symbol           | Value    | Unit |
|--|------------------|----------|------|
| Power dissipation                      | P <sub>d</sub>   | 72       | mW   |
| Forward current                        | I <sub>F</sub>   | 30       | mA   |
| Reverse voltage                        | V <sub>R</sub>   | 5        | V    |
| Operating temperature range            | T <sub>op</sub>  | -40 ~+80 | °C   |
| Storage temperature range              | T <sub>stg</sub> | -40 ~+85 | °C   |
| Peak pulsing current (1/8 duty f=1kHz) | I <sub>FP</sub>  | 125      | mA   |

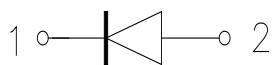
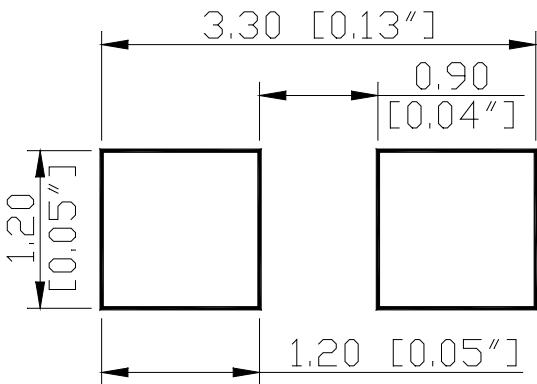
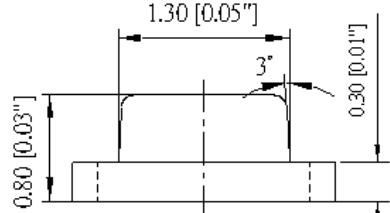


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## PACKAGING DIMENSIONS (mm):



RECOMMEND PAD LAYOUT



### Precautions For Use :

#### Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen )

#### Storage

1. The operation of temperature and R.H. are :  $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$ , 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent. Considering the tape life, we suggest our customers to use our products within 1.5 year ( from production date ).
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is :  $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 15hrs.



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## ■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

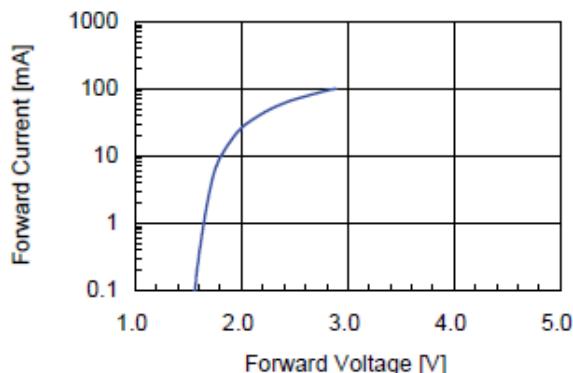


Fig 3. Forward Voltage vs. Temperature

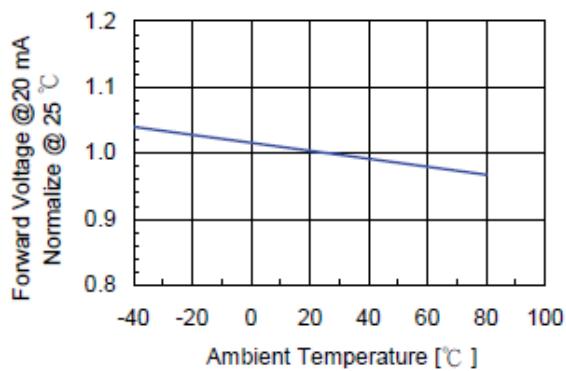


Fig 5. Relative Intensity vs. Wavelength

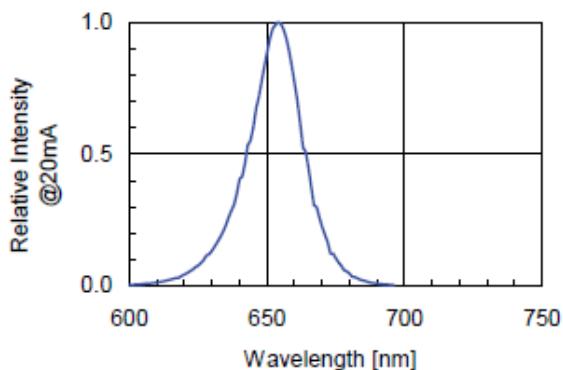


Fig 2. Relative Intensity vs. Forward Current

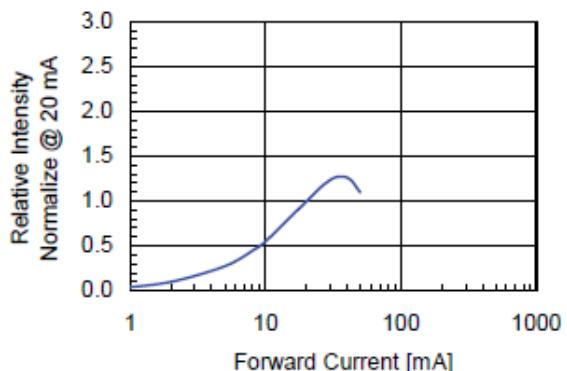
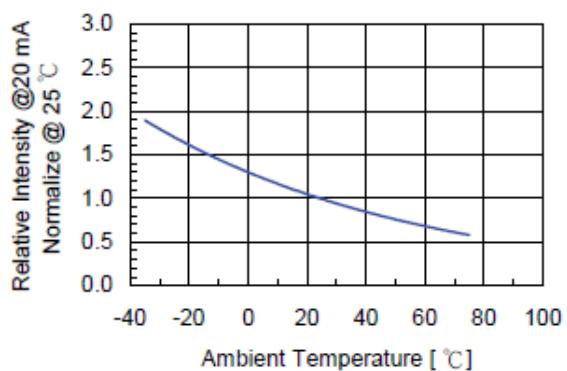
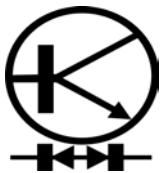


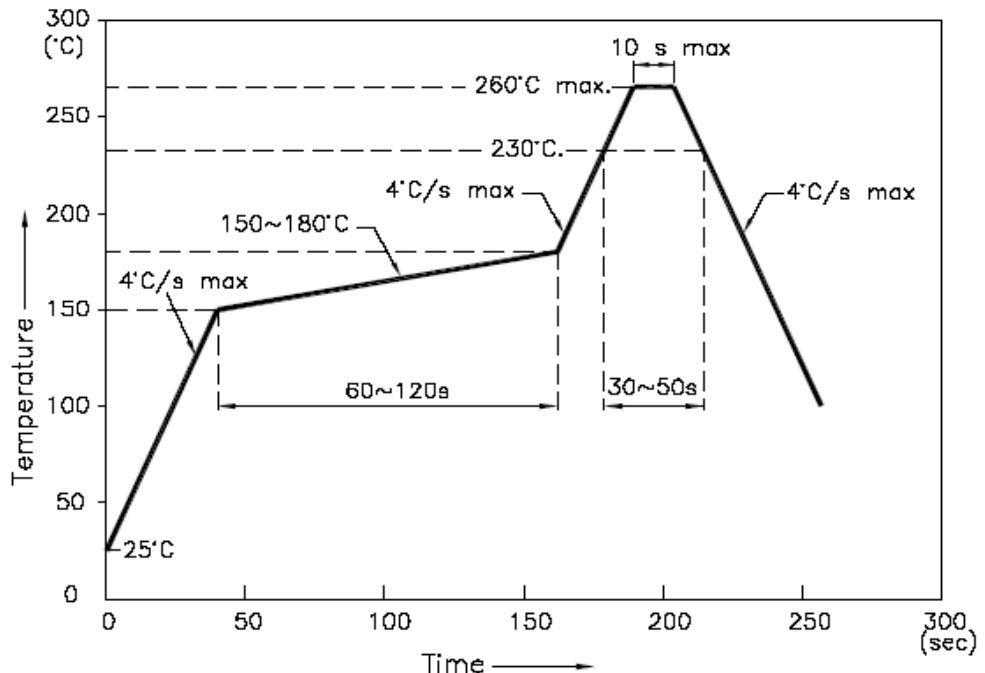
Fig 4. Relative Intensity vs. Temperature





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## ■ Reflow Temp/Time



## NOTES:

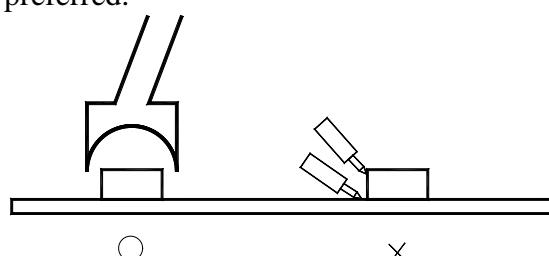
1. We recommend the reflow temperature  $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$ . the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

## ■ Soldering iron

Basic spec is  $\leq 5\text{ sec}$  when  $260^{\circ}\text{C}$  . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{ sec}$  ).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under  $230^{\circ}\text{C}$  .

## ■ Rework

1. Customer must finish rework within 5 sec under  $260^{\circ}\text{C}$  .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



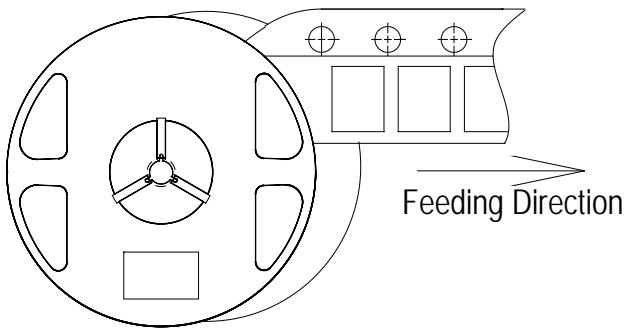
- Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow , solder etc.



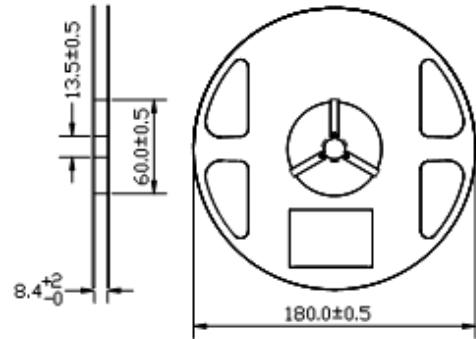
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## Packaging Specifications

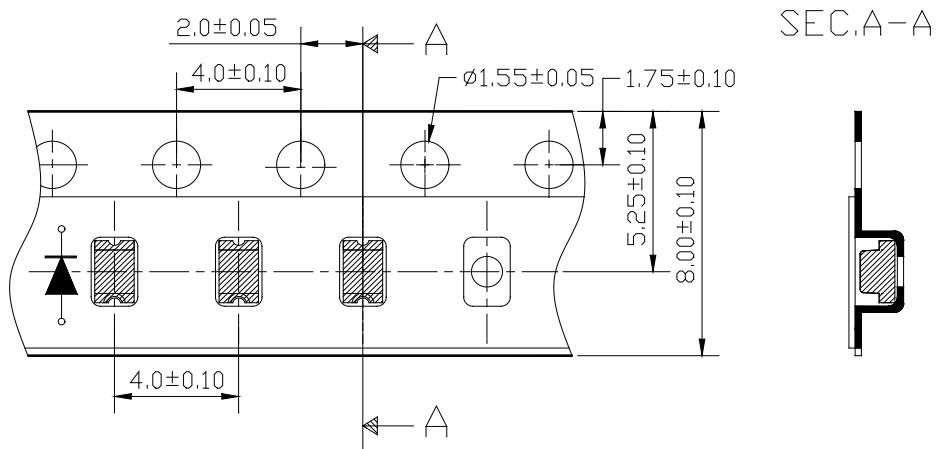
- Feeding Direction



- Dimensions of Reel (Unit: mm)



- Dimensions of Tape (Unit: mm)



- Arrangement of Tape

